Title (en)
DEVICE AND METHOD FOR TREATING ELECTROCONDUCTIVE ENDLESS MATERIAL

Title (de)
VORRICHTUNG UND VERFAHREN ZUR BEHANDLUNG VON ELEKTRISCH LEITFÄHIGEM ENDLOSMATERIAL

Title (fr)
PROCEDE ET DISPOSITIF POUR TRAITER UN MATERIAU CONTINU ELECTROCONDUCTEUR

Publication
EP 1080250 A1 20010307 (DE)

Application
EP 00909243 A 20000223

Priority
• DE 19907911 A 19990224
• EP 0001490 W 20000223

Abstract (en)
[origin: WO0050667A1] Disclosed is a device for treating electroconductive endless material (3) such as wire, especially copper wire. The inventive devices treats said material during the movement of the endless material and in the extension direction thereof and can be used for heating or annealing the endless material or for cleaning the surface thereof. The inventive device comprises a contact device (15) for electrically contacting the moved endless material (3) and an electrode arrangement (17) which is arranged at a distance from the endless material (3) and which at least partially encompasses the endless material. A gas discharge chamber (11) is arranged between the endless material (3) and the electrode arrangement (17) and is filled with a reaction gas. A voltage is impressed across the contact device (5) and the electrode arrangement (17) and in said gas discharge chamber (11). An electric gas discharge can thus be produced in order to treat the endless material (3).

IPC 1-7
C23G 5/00; B08B 7/00

IPC 8 full level
B08B 7/00 (2006.01); **C23G 5/00** (2006.01); **F27B 9/02** (2006.01); **F27B 9/06** (2006.01); **F27B 9/28** (2006.01); **F27B 9/36** (2006.01); **F27D 11/08** (2006.01); **F27D 11/10** (2006.01); **F27D 19/00** (2006.01)

CPC (source: EP KR US)
B08B 7/0035 (2013.01 - EP US); **C23G 5/00** (2013.01 - EP KR US); **H01J 37/32577** (2013.01 - EP US); **H01J 37/3277** (2013.01 - EP US)

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 0050667 A1 20000831; AU 3159700 A 20000914; CA 2328468 A1 20000831; CN 1294640 A 20010509; CZ 20004352 A3 20011212; DE 19907911 A1 20000921; DE 19907911 C2 20030227; EP 1080250 A1 20010307; HR P20000715 A2 20010430; HU P0102713 A2 20011228; HU P0102713 A3 20030428; JP 2002543273 A 20021217; KR 20010042949 A 20010525; MX PA00010282 A 20030422; PL 343679 A1 20010827; SI 20480 A 20010831; SK 15382000 A3 20010510; TR 200002875 T1 20010122; US 2001026781 A1 20011004; US 6471920 B2 20021029; YU 63800 A 20030131; ZA 200006866 B 20010903

DOCDB simple family (application)
EP 0001490 W 20000223; AU 3159700 A 20000223; CA 2328468 A 20000223; CN 00800205 A 20000223; CZ 20004352 A 20000223; DE 19907911 A 19990224; EP 00909243 A 20000223; HR P20000715 A 20001023; HU P0102713 A 20000223; JP 2000601227 A 20000223; KR 20007011774 A 20001023; MX PA00010282 A 20000223; PL 34367900 A 20000223; SI 200020001 A 20000223; SK 15382000 A 20000223; TR 200002875 T 20000223; US 67394300 A 20001024; YU P63800 A 20000223; ZA 200006866 A 20001123